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PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
WOLF HUNG	05/21/2013
CHUNG-NAN CHEN	05/21/2013
JAW-LIH SHIH	05/21/2013
HONG-HSING CHOU	05/22/2013
YEH-CHIEH WANG	05/22/2013

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	8, LI-HSIN RD. 6
Internal Address:	HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78

PROPERTY NUMBERS Total: 1

Property Type	Number				
Application Number:	17403540				

CORRESPONDENCE DATA

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Address Line 2: SUITE 700

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ATTORNEY DOCKET NUMBER:	2012-1381/24061.2543US03
NAME OF SUBMITTER:	EFFEI DAH
SIGNATURE:	/Effei Dah/
DATE SIGNED:	08/16/2021

PATENT REEL: 057194 FRAME: 0095 506820059

Total Attachments: 3

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PATENT REEL: 057194 FRAME: 0096

Docket No.: 2012-1381/24061.2543 Customer No.: 000042717

ASSIGNMENT

WHEREAS, we

,	,		
(1)	WolfHung	of	28, 96 Tunnel, Young-Min Road, Hsinchu Hsin-pu town, Taiwan, R.O.C.
(2)	Chung-Nan Chen	of	No. 48, Lane 61, Shangyi Street Hsinchu County 302 Zhubei City, Taiwan, R.O.C.
(3)	Jaw-Lih Shih	of	No. 10, Alley 5, Lane 289 Syuefu E Road Hsinchu County 310 Jhudong Township, Taiwan, R.O.C.
(4)	Hong-Hsing Chou	of	3F, No. 282, Wunping Road Hsinchu County 30264 Jhubei City, Taiwan, R.O.C.
(5)	Yeh-Chieh Wang	of	4F., No. 29, Lane 145, Baoshan Road, 300 Hsinchu City, Taiwan, R.O.C.

have invented certain improvements in

SYSTEMS AND METHODS FOR A NARROW BAND HIGH TRANSMITTANCE INTERFERENCE FILTER

for	which	we	have	executed	an	application	for	Letters	Patent	of the	United	States	of.	Amer	ica,
		Х		of even	dat	e filed here	wit	h; and							

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

filed on ______ and assigned application number _____; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize

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and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:	Wolf Hung	
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Dated: May,	2 ,20/3	No 1 Hung Inventor Signature
A		
Inventor Name:	Chung-Nan Chen	
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Dated: May->1	-7013	Chung-Nan Chen Inventor Signature
·	•	Inventor Signature
Inventor Name:	Jaw-Lih Shih	, , , , , , , , , , , , , , , , , , , ,
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		· · · · · · · · · · · · · · · · · · ·

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Dated: May. 22 2013

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